IEEE ELECTRONICS PACKAGING SOCIETY

IEEE Advancing Technology for Humanity

IEEE EPS Switzerland chapter
Technical Presentation Session

Packaging of Electronic Devices

Sonova Stäfa, 13th June 2018

As part of the course of regular technical presentation sessions, EPS Switzerland chapter is organizing a session about packaging of electronic devices.
The goal of this seminar is to provide a platform where people can exchange information about their activities, interests and solutions.

Program

14:30 – 14:35 EPS Welcome and introduction
Daniel Thommen, IEEE EPS chapter chair, Development Manager, Microdul AG

14:35 – 14:50 Sonova Company Intro
Gerard van Oerle, Director HI Microsystems, Sonova

14:50 – 15:15 3D-MID for Space Applications
Dr. Etienne Hirt, R+D Director, Art of Technology, Zurich
3D-MID allows combining enclosure or other mechanical elements with the routing and component mounting of a PCB. It is currently used in automotive, mobile phones and hearing aids. Our aim is to make 3D-MID technologies available for space applications. We will present the work we currently perform in an ESA ARTES project. After an evaluation of suitable 3D-MID technologies for space applications, the selection was verified with reliability tests. Currently we are designing and building demonstrators (sun sensor and helix antenna) that will be subject to qualification.

15:15 – 15:40 Electronic Packaging for Hearing Devices: Balancing act between product innovation and standardization
Michael Mathey, Senior Manager Process Development, Sonova.
Modern Hearing Devices must provide sophisticated sound processing and wireless connectivity to meet the customers’ expectations. Electronic Packaging technology can play a significant role in allowing a device with these features to have a small size and a long useful life. At the same time the economics of mass production demand the use of standard components and production techniques. Can innovative packaging solutions be combined with product standardization?

15:40 – 16:10 Election
Daniel Thommen, Slavo Kicin, Rony Jose James IEEE EPS Chapter Management

16:20 – 17:20 Factory Tour
Dietmar Popov, Director Corporate Manufacturing Engineering, Sonova

17:20 – 18:00 Apéro / Networking

Location: Sonova AG, Laubisruetistrasse 28, 8712 Staefa, Switzerland
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Please register by E-mail (daniel.thommen@microdul.com) before 28th May 2018